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TUNG et al.(10) **Pub. No.: US 2022/0386512 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **ELECTRONIC DEVICE AND HEAT DISSIPATION ASSEMBLY**(71) Applicants: **Inventec (Pudong) Technology Corporation**, Shanghai (CN);
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(57)

ABSTRACT

An electronic device connected to external heat dissipation device and including chassis, heat source, and heat dissipation assembly. Heat dissipation assembly includes evaporator, tubing, and liquid-cooling plate. Evaporator is in thermal contact with heat source. Tubing includes evaporation portion and condensation portion. Evaporation portion is in fluid communication with condensation portion and in thermal contact with evaporator. Liquid-cooling plate is disposed on chassis and spaced apart from heat source. Liquid-cooling plate includes liquid-cooling accommodation space and is configured to be in fluid communication with external heat dissipation device. Condensation portion is located in liquid-cooling accommodation space. Condensation portion includes first tube part, second tube part and connecting tube parts. Two opposite ends of each connecting tube part are respectively in fluid communication with first and second tube parts. Connecting tube parts are connected in parallel. First and second tube parts are in fluid communication with evaporation portion.

